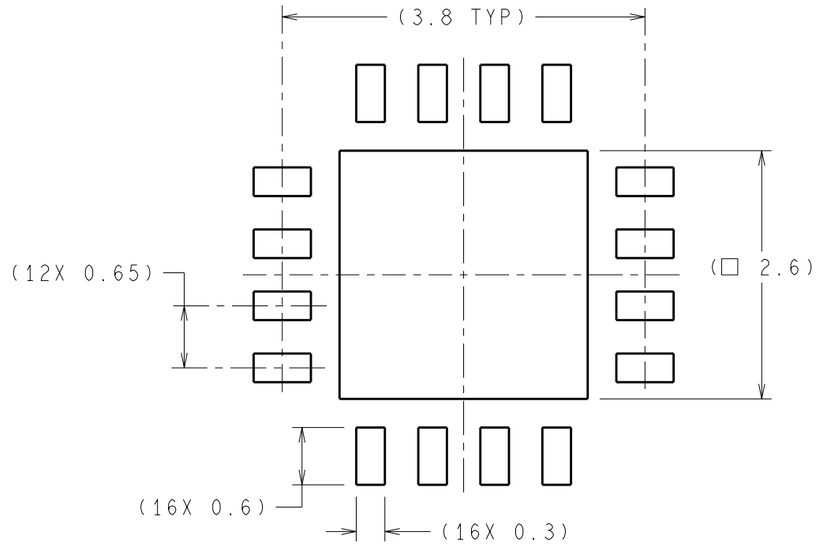
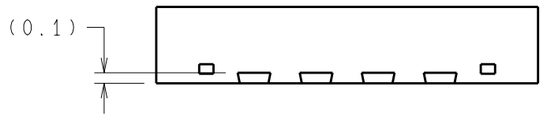
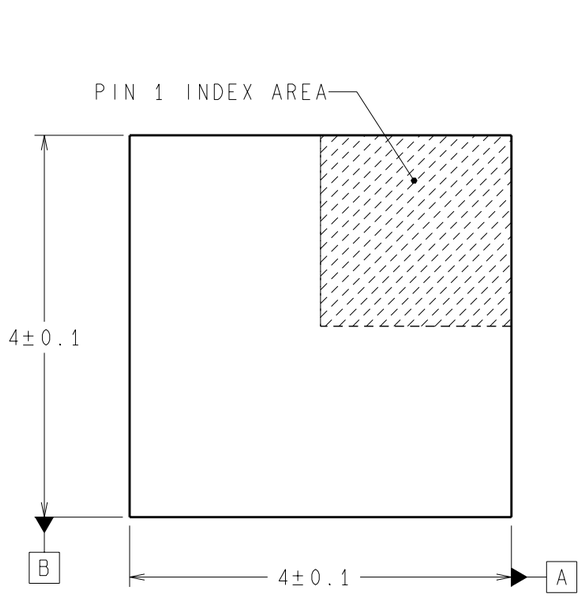
| REVISIONS | | | | |
|---|---|---|---|---|
| REV | DESCRIPTION | E.C.N. | DATE | BY/APP'D |
| A | RELEASE TO DOCUMENT CONTROL | 1974 | 12/01/2005 | AS/TL/AS |

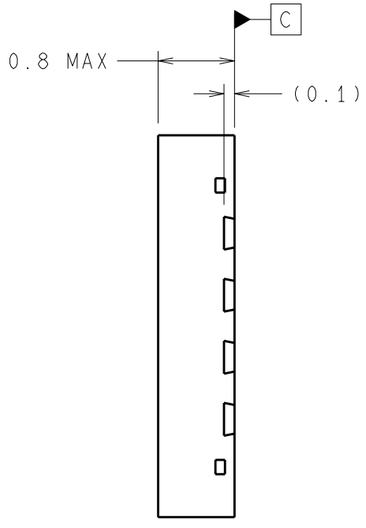


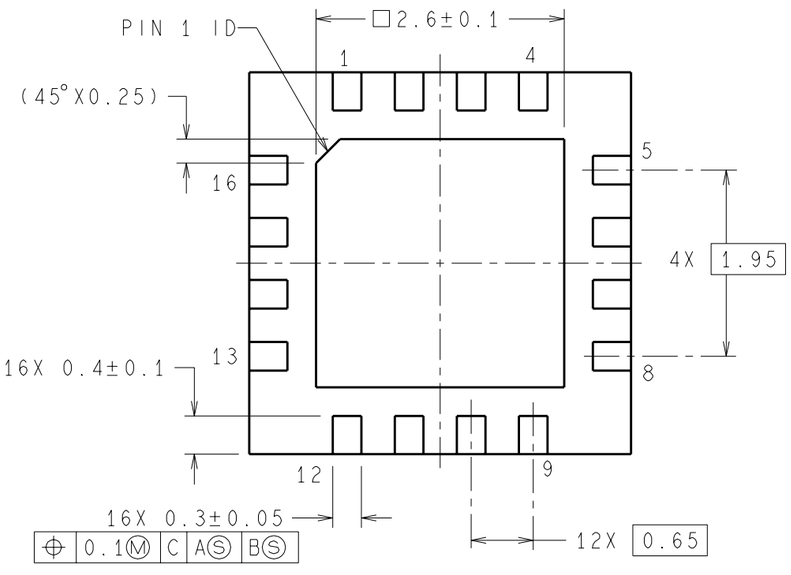

**RECOMMENDED LAND PATTERN**

**DIMENSIONS ARE IN MILLIMETERS**
DIMENSIONS IN ( ) FOR REFERENCE ONLY




NOTES: UNLESS OTHERWISE SPECIFIED

1. FOR SOLDER THICKNESS AND COMPOSITION, SEE "SOLDER INFORMATION" IN THE PACKAGING SECTION OF THE NATIONAL SEMIONDUCTOR WEB PAGE (www.national.com).
2. MAXIMUM ALLOWABLE METAL BURR ON LEAD TIPS AT THE PACKAGE EDGES IS 76 MICRONS.
3. REFERENCE JEDEC REGISTRATION MO-220, VARIATION WGGC-2.

| APPROVALS | DATE |
|---|---|
| DRAWN A. SULAIMAN & TL | 12/01/2005 |
| DFTG. CHK. THANH LEQUANG | 12/01/2005 |
| ENGR. CHK. A. SULAIMAN | 12/01/2005 |

PROJECTION MM

National Semiconductor
2900 Semiconductor Dr, Santa Clara, CA 95052-8090

LLP, PLASTIC, QUAD,
4x4x0.8mm,16 LD,
0.65mm PITCH, NO PULLBACK

| SCALE | SIZE | DRAWING NUMBER | REV |
|---|---|---|---|
| NTS | B | (SC)MKT-SQB16A | A |

FORMERLY: N/A SHEET 1 of 1